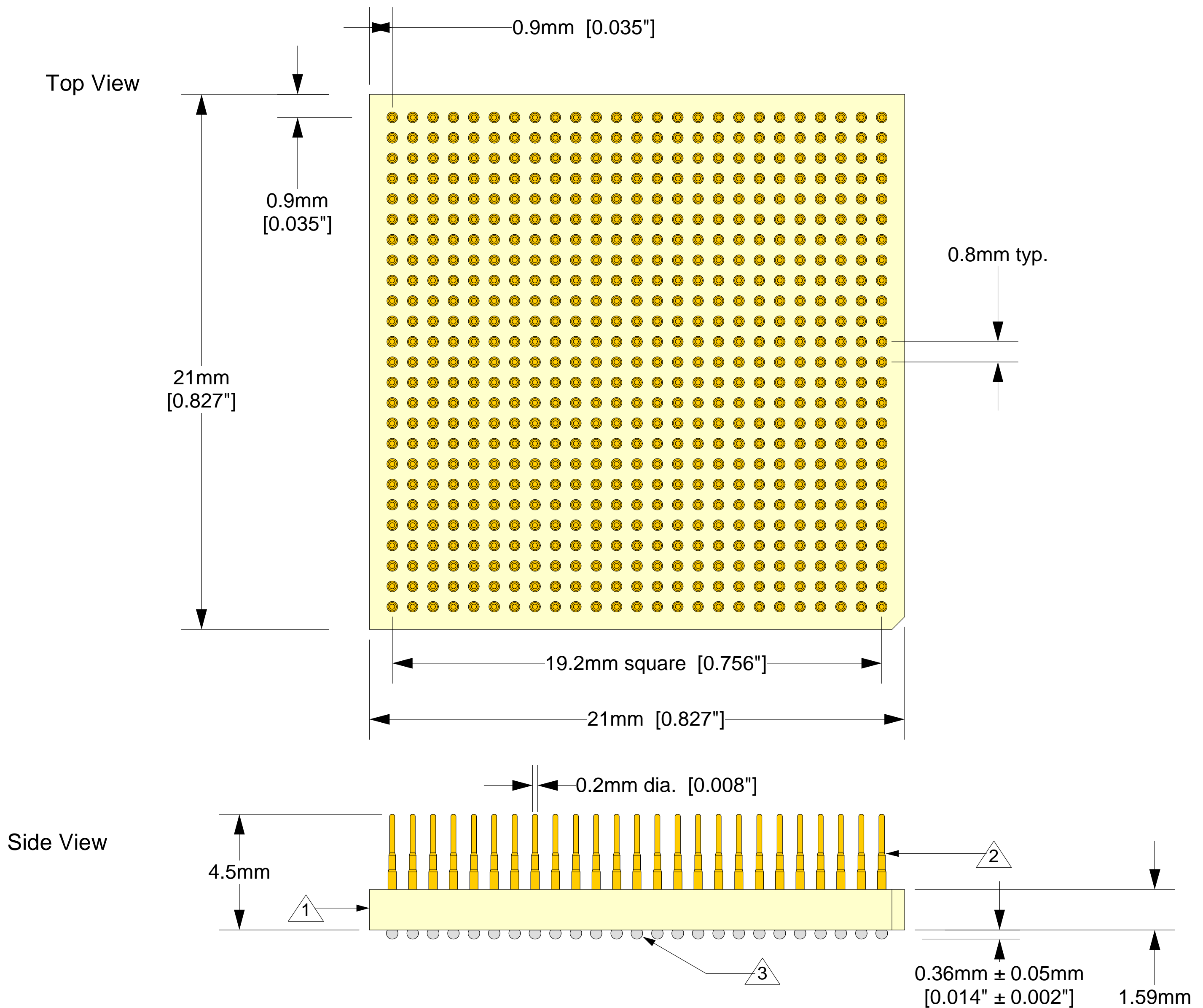

1. Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material; Non-clad
2. Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
3. Solder Balls: Sn96.5Ag3.0Cu0.5

RoHS COMPLIANT

Description: Giga-snaP BGA SMT Foot
625 position terminal pins (0.8mm centers, 25x25 array) to SMT solder balls (BGA type). Pin asignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA625C-B-61F Drawing	Status: Released	Scale: 4:1	Rev: B
© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: A. Evans	Date: 05/28/09	
	File: SF-BGA625C-B-61F Dwg.mcd	Modified: 09/03/14	